

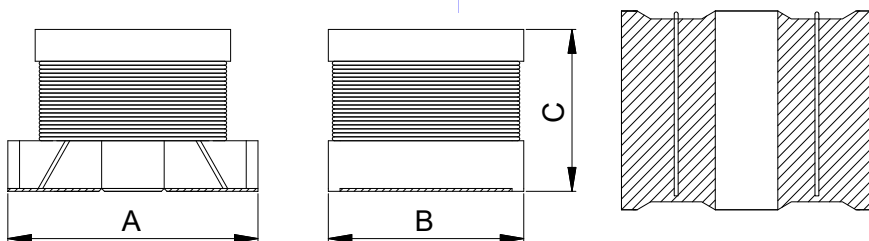
### Features

- \* RoHS compliant
- \* This miniature chip inductors wound on a special ferrite core.
- \* High Q value at high frequencies and low DC resistance.
- \* Wide inductance range.
- \* Excellent solder heat resistance. Both flow and reflow soldering methods can be employed.

### Applications

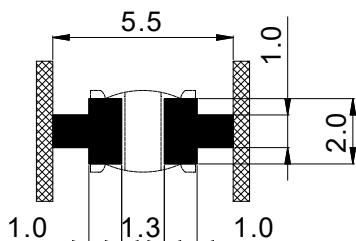
- \* Personal, Cordless phone.
- \* High Freq. Communication Products.
- \* GPS (Global Position System).
- \* Personal computers.

### Appearance and Dimensions

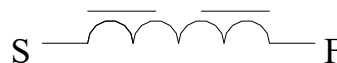


Dimensions(mm)						
Series	A	B	C	D	E	F
ESQV322520	3.2±0.3	2.5±0.2	2.0±0.2	-	-	-

### Land Pattern Dimensions



### Circuit Diagram



### Product Identification

ESQV - 322520 T - 5R6 M - N

- ①      ②      ③      ④      ⑤      ⑥

- ① Product Symbol
- ② Dimensions
- ③ Packaging
- ④ Inductance (R56:0.56μH; 5R6:5.6μH; 560:56μH; 561:560μH)
- ⑤ Inductance Tolerance (K:10% ; M:20%)
- ⑥ RoHS

### Electrical Characteristics

Part No.	Inductance	Tolerance	Test Frequency	Quality Factor min.	Test Frequency	DC Resistance max.	Self-resonant Frequency min.	Rated current typ.
Unit	μH	%	MHz	-	MHz	Ω	MHz	mA
Symbol	L	Tol.	-	Q	-	R <sub>DC</sub>	f <sub>res</sub>	I <sub>R</sub>
ESQV322520T-R10□-N	0.10	±20	1.000	20	25.20	0.025	200	700
ESQV322520T-R18□-N	0.18	±20	1.000	20	25.20	0.250	200	650
ESQV322520T-R27□-N	0.27	±20	1.000	25	25.20	0.250	200	600
ESQV322520T-R39□-N	0.39	±20	1.000	25	25.20	0.250	200	530
ESQV322520T-R56□-N	0.56	±20	1.000	30	25.20	0.250	160	530
ESQV322520T-R68□-N	0.68	±20	1.000	30	25.20	0.250	160	470
ESQV322520T-R82□-N	0.82	±20	1.000	30	25.20	0.250	120	450
ESQV322520T-1R0□-N	1.00	±20	1.000	20	1.000	0.500	100	445
ESQV322520T-1R2□-N	1.20	±20	1.000	20	1.000	0.600	100	425
ESQV322520T-1R5□-N	1.50	±20,±10	1.000	20	1.000	0.600	75.0	400
ESQV322520T-1R8□-N	1.80	±20,±10	1.000	20	1.000	0.700	60.0	390
ESQV322520T-2R2□-N	2.20	±20,±10	1.000	20	1.000	0.800	50.0	370
ESQV322520T-2R7□-N	2.70	±20,±10	1.000	20	1.000	0.900	43.0	320
ESQV322520T-3R3□-N	3.30	±20,±10	1.000	20	1.000	1.000	38.0	300
ESQV322520T-3R9□-N	3.90	±20,±10	1.000	20	1.000	1.100	35.0	290
ESQV322520T-4R7□-N	4.70	±20,±10	1.000	20	1.000	1.200	31.0	270
ESQV322520T-5R6□-N	5.60	±20,±10	1.000	20	1.000	1.300	28.0	250
ESQV322520T-6R8□-N	6.80	±20,±10	1.000	20	1.000	1.500	25.0	240
ESQV322520T-8R2□-N	8.20	±20,±10	1.000	20	1.000	1.600	23.0	225
ESQV322520T-100□-N	10.0	±10,±5	1.000	35	1.000	1.800	20.0	190
ESQV322520T-120□-N	12.0	±10,±5	1.000	35	1.000	2.000	18.0	180
ESQV322520T-150□-N	15.0	±10,±5	1.000	35	1.000	2.200	16.0	170
ESQV322520T-180□-N	18.0	±10,±5	1.000	35	1.000	2.500	15.0	165
ESQV322520T-220□-N	22.0	±10,±5	1.000	35	1.000	2.800	14.0	150
ESQV322520T-270□-N	27.0	±10,±5	1.000	35	1.000	3.100	13.0	125
ESQV322520T-330□-N	33.0	±10,±5	1.000	40	1.000	3.500	12.0	115

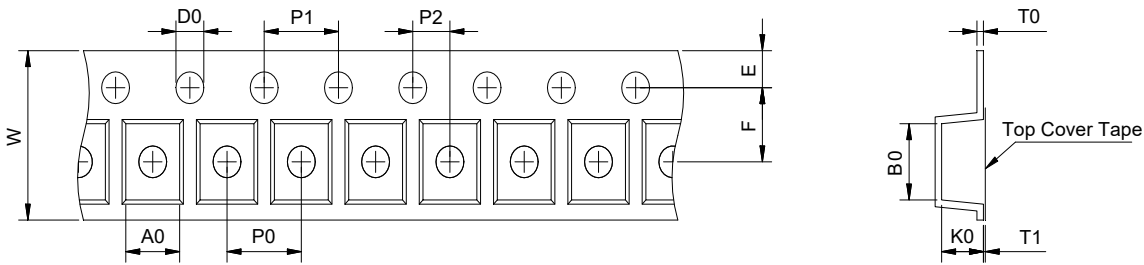
ESQV322520T-390□-N	39.0	±10,±5	1.000	40	1.000	3.900	11.0	110
ESQV322520T-470□-N	47.0	±10,±5	1.000	40	1.000	4.300	11.0	100
ESQV322520T-560□-N	56.0	±10,±5	1.000	40	1.000	4.900	10.0	85.0
ESQV322520T-680□-N	68.0	±10,±5	1.000	40	1.000	5.500	9.00	80.0
ESQV322520T-820□-N	82.0	±10,±5	1.000	40	1.000	6.200	8.50	70.0
ESQV322520T-101□-N	100	±10,±5	1.000	40	0.796	7.000	8.00	80.0
ESQV322520T-121□-N	120	±10,±5	1.000	40	0.796	8.000	7.50	75.0
ESQV322520T-151□-N	150	±10,±5	1.000	40	0.796	9.300	7.00	70.0
ESQV322520T-181□-N	180	±10,±5	1.000	40	0.796	10.20	6.00	65.0
ESQV322520T-221□-N	220	±10,±5	1.000	40	0.796	11.80	5.50	65.0
ESQV322520T-271□-N	270	±10,±5	1.000	40	0.796	12.50	5.00	65.0
ESQV322520T-331□-N	330	±10,±5	1.000	40	0.796	13.00	5.00	65.0
ESQV322520T-391□-N	390	±10,±5	1.000	50	0.796	22.00	5.00	50.0
ESQV322520T-471□-N	470	±10,±5	0.001	50	0.796	25.00	5.00	45.0
ESQV322520T-561□-N	560	±10,±5	0.001	50	0.796	28.00	2.00	40.0

**Remark:**

- ※1: All test data is referenced to 20°C ambient.
- ※2: Q: The power periodically exchanged between an inductor and a power source in an AC circuit.
- ※3: Self-resonant Frequency: The self-resonant frequency is the high-frequency critical point of practical passive components.
- ※4: DC Resistance: DC resistance at 20°C.
- ※5: Rated current:  $I_{SAT}$  or  $I_{RMS}$ , whichever is smaller.
- ※6: Saturation Current: max. Value, DC current at which the inductance drops less than 30% from its value without current.
- ※7: Heat Rating Current: DC current that causes the temperature rise ( $\Delta T$ ) from 20°C ambient,  
for typ. Value,  $\Delta T$  is approximate 40°C.
- ※8: Specifications subject to change without notice. Please check our website for latest information.

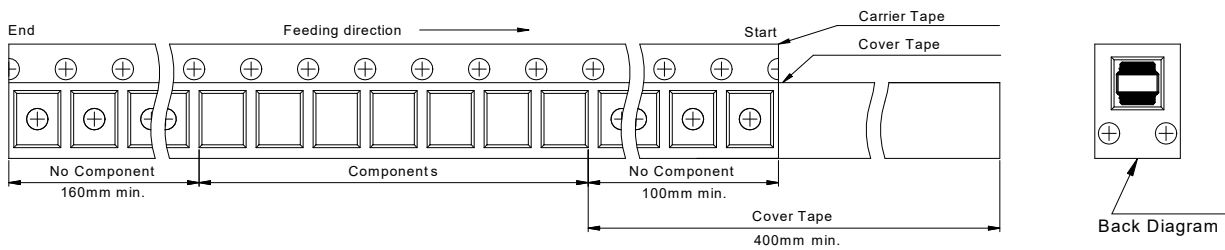
### Packing specification

#### Carrier tape dimensions (mm)



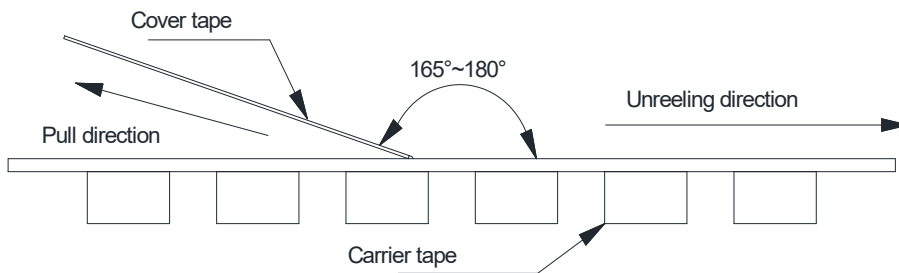
ITEM	W	P0	E	F	T0	T1	A0	B0	K0	D0	P1	P2
Size(mm)	8.00	4.00	1.75	3.50	0.35	0.10	2.90	3.60	2.25	1.50	4.00	2.00
Tolerance	±0.30	±0.10	±0.10	±0.10	ref.	max.	typ.	typ.	typ.	±0.10	±0.10	±0.10

#### Taping dimensions (mm)

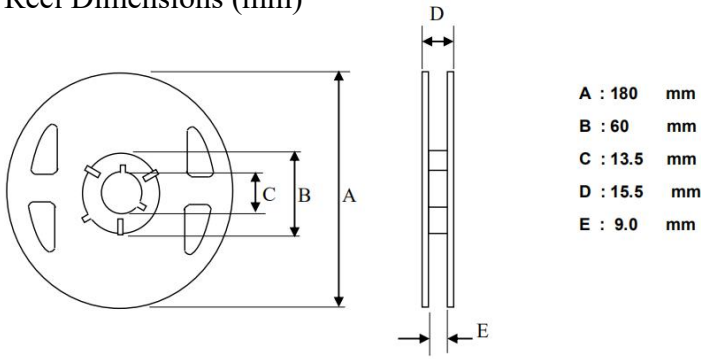


#### Cover Tape Peel Off Condition

Cover tape peel force shall be 10g to 130g.



### Reel Dimensions (mm)



### Packing Quantity

Product Series	Quantity/Reel	Inner Carton Quantity	Outer Carton Quantity
ESQV322520	2000Pcs	(2000X6)=12000pcs	(12000X3)=36000pcs



### Recommended Soldering Conditions

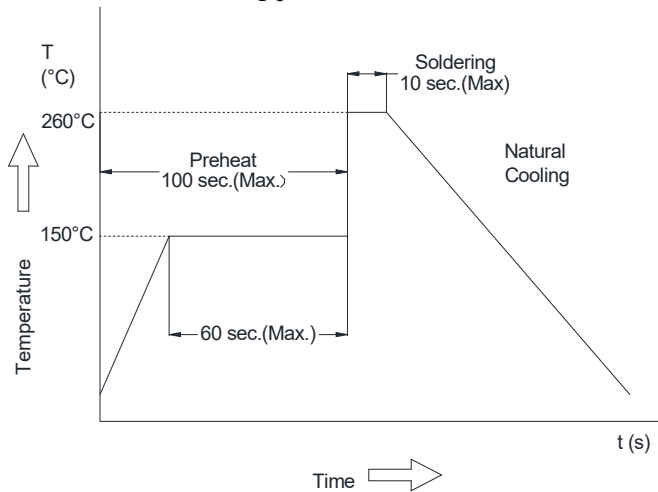
Product can be applied to flow and reflow soldering.

(1) Flux, Solder

- ① Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).
- ② Use Sn solder.

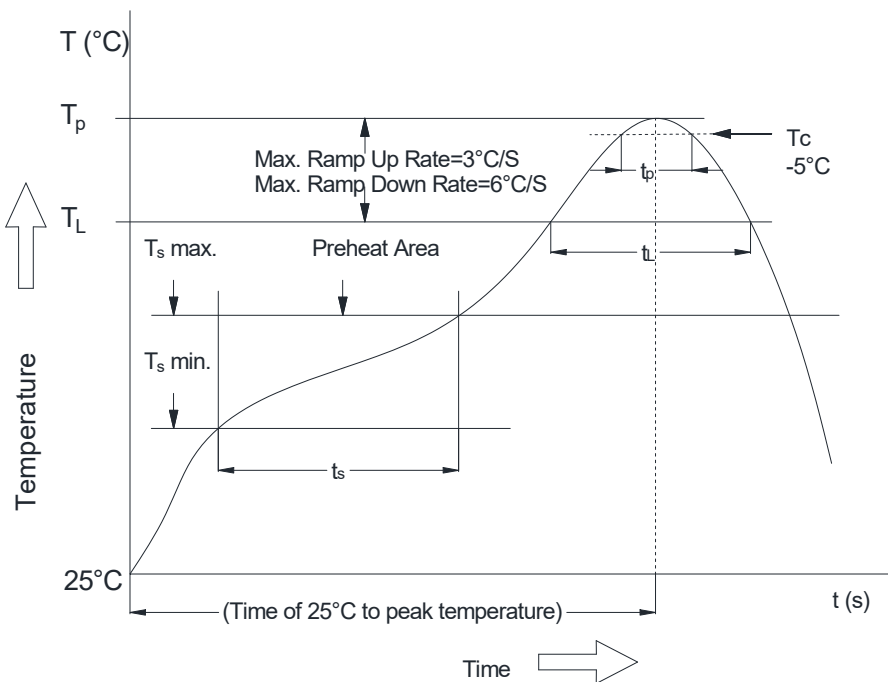
(2) Flow soldering conditions

- ① Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100°C max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- ② Standard soldering profile.



(3) Reflow soldering conditions

Classification Reflow Profile for SMT components:



Classification Reflow Soldering Profile:

Profile Feature		Lead-Free Assembly
Average Ramp-Up Rate (Ts max. to Tp)		3°C/second max.
Preheat	- Temperature Min (Ts min.)	150°C
	- Temperature Max (Ts max.)	200°C
	- Time (Ts min to Ts max.)	60-120 seconds
Time maintained above	- Temperature (TL)	217°C
	- Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)		see table below
Peak/Classification Time (Tp)		3-4 seconds
Time within 5 °C of actual Peak Temperature (tp)		20-30 seconds
Ramp-Down Rate		6°C/second max.
Time 25 °C to Peak Temperature		8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

2: Refer to IPC/ JEDEC J-STD-020E

Package Classification Reflow Temperature:

Properties	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
PB-Free Assembly   Package Thickness < 1.6 mm	260°C	260°C	260°C
PB-Free Assembly   Package Thickness 1.6mm-2.5 mm	260°C	250°C	245°C
PB-Free Assembly   Package Thickness ≥2.5 mm	250°C	245°C	245°C

Refer to IPC/ JEDEC J-STD-020E

(4) The method on Re-work with using the iron:

The following conditions must be strictly followed when using a soldering iron

Pre-heating	150°C, 1 minute
Tip temperature	280°C max
Soldering iron output	20w max
End of soldering iron	φ1mm max
Soldering time	3 seconds max

## Products Storage

(1) Storage period

Products which inspected in LYEC over 12 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solderability should be checked if this period is exceeded.

(2) Storage conditions

Products should be storage in the warehouse on the following conditions:

Temperature: Less than 40°C

Humidity : Less than 75% relative and humidity

No rapid change on temperature and humidity

- (3) Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- (4) Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.
- (5) Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- (6) Products should be storage under the airtight packaged condition.